

CUSTOMER SPECIFIC OVENS



Model	RSS-3X210	VSS-450-300-L	2Z-HVS-200
Application	Solder Reflow System with Liftpins	Solder Reflow System (3 Modules with 1 controller) with Liftpins	High Vacuum Sealer for MEMS
Qty of substrates	12 wafers 100 mm dia.	for 5 pcs wafers 4" or 4 pcs 5" per module	for 6 adapters each with 42mm dia
T _{max}	300 °C	450 °C	bottom: 450 °C, top: 200 °C
Ramp up rate	120 K/min	120 K/min	20 K/min (in vacuum)
Vacuum up to	10 ⁻³ hPa	10 ⁻³ hPa	10 ⁻⁶ hPa
Flowmeter	FM digital	FM digital	FM digital
Controller	Eurotherm	Eurotherm	Eurotherm